

STRUCTURE	Silicon Monolithic Integrated Circuit
PRODUCT SERIES	2-Phase Half-Wave Pre Driver for Fan Motor
TYPE	<b>B D 6 7 1 2 A F</b>
FEATURES	Built - in zenner diode for Vcc clamp

**○ABSOLUTE MAXIMUM RATINGS**

Parameter	Symbol	Limit	Unit
Power dissipation	Pd	780 *	mW
Operating temperature	Topr	-35~+95	°C
Storage temperature	Tstg	-55~+150	°C
Output current	Iomax	40	mA
AL Signal output current	I <sub>AL</sub>	15	mA
AL Signal output voltage	V <sub>AL</sub>	60	V
Junction temperature	T <sub>jmax</sub>	150	°C

\* To use at temperature above Ta=25°C reduce 6.24mW/°C.  
 (On 70.0mm × 70.0mm × 1.6mm glass epoxy board)

**○OPERATING CONDITIONS**

Parameter	Symbol	Limit	Unit
Operating supply voltage range	Vcc	3.5~Vcz	V
Operating supply current range	Icc	1~30	mA
FG output voltage range, AL output voltage range	V <sub>SI</sub>	0~48	V
Hall input voltage range	V <sub>H</sub>	0~Vcz-1.5	V

\* This product is not designed for production against radioactive rays.  
 \* This document may be strategic data subject to COCOM regulations.

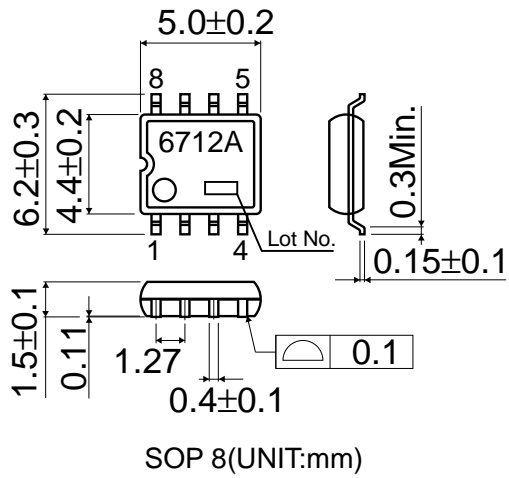
## ○ELECTRICAL CHARACTERISTICS (Unless otherwise specified Ta=25°C,Vcc=5V)

Parameter	Symbol	Limit			Unit	Conditions
		Min.	Typ.	Max.		
Internal voltage	Vcz	5.5	6.0	6.5	V	Icc=10mA
Circuit current1	Icc1	0.5	1.5	3.0	mA	*
Circuit current2	Icc2	4	6.7	9.5	mA	* *
Hall input hysteresis voltage	Vhys	5	15	25	mV	
Lock detection ON time	TON	0.25	0.5	1	sec	
Lock detection OFF time	TOFF	2.5	5	10	sec	
Output H voltage	VOH	Vcc-0.5	Vcc-0.2	Vcc	V	I <sub>o</sub> =-10mA
Output L voltage	VOL	-	0.2	0.5	V	I <sub>o</sub> =10mA
Hall output L voltage	VFGL	-	0.15	0.5	V	I <sub>FG</sub> =5mA
Hall output leak current	IFGL	-	0	10	μA	V <sub>FG</sub> =48V
Alarm output L voltage	VALL	-	0.15	0.5	V	I <sub>AL</sub> =5mA
Alarm output leak current	IALL	-	0	10	μA	V <sub>AL</sub> =48V

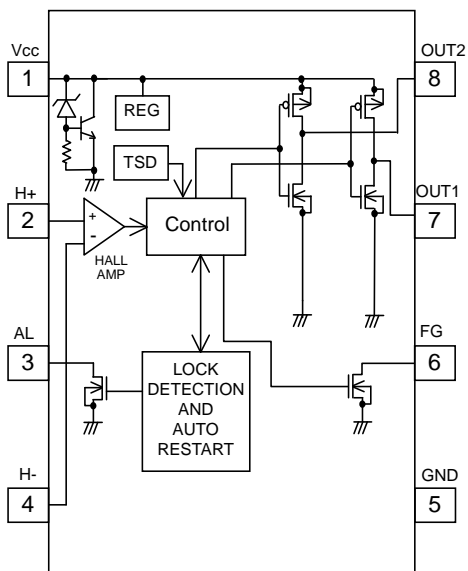
\* H+:3V,H-:2V,Output,FG,AL terminal are open.

\* \* Hall-input is 100Hz square wave.Output is connected with 1kΩ to ground.  
 FG and AL are connected with 50kΩ to Vcc.

○PACKAGE OUTLINES



○BLOCK DIAGRAM



○Terminal name

Pin No.	Terminal name
1	Vcc
2	H+
3	AL
4	H-
5	GND
6	FG
7	OUT1
8	OUT2

## OCAUTIONS

- 1) Absolute maximum ratings  
There is possibility of destruction in using beyond the absolute maximum rating. In case of destruction, a failure mode can not be defined (short mode or open mode). Therefore when special mode is envisaged where absolute maximum rating may be exceeded, please take a physical safety measure such as fuse.
- 2) Reverse connection of power supply connector  
Reverse connection of power supply connector may break IC. Take a measure against reverse connection destruction such as inserting a diode between power supply and Vcc terminal.
- 3) Power supply line  
Back electromotive force causes regenerated current to power supply line, therefore take a measure such as placing a capacitor between power supply and GND for routing regenerated current, and fully ensure that the capacitor characteristics have no problem before determine a capacitor value
- 4) GND potential  
Ensure that the potential of GND terminal is the minimum potential in any operating condition. Also ensure that all terminals except GND terminal do not fall below GND voltage including transient characteristics. However, it is possible that the motor output terminal may deflect below GND because of influence by back electromotive force of motor. Malfunction may possibly occur depending on use condition, environment, and property of individual motor. Please make fully confirmation that no problem is found on operation of IC.
- 5) Thermal design  
Consider the power dissipation under actual use condition and apply thermal design with sufficient margin.
- 6) Mounting failures  
In attaching IC to printed board, pay enough attention to the direction and dislocation of IC. Mounting failures may break IC. In addition, destruction is also possible when circuit is shorted by foreign substance brought between outputs or between output and power supply - GND.
- 7) Operation in strong electromagnetic field  
Use in strong electromagnetic field may cause malfunction, please be careful.
- 8) ASO  
Please consider that the output Tr does not exceed the absolute maximum rating and ASO.
- 9) Thermal shut down circuit  
This IC has thermal shut down (TSD) circuit. Operation temperature is 175°C(typ.) and has a hysteresis width of 25°C(typ.). When IC chip temperature rises and TSD circuit works, the output terminal becomes an open state. TSD circuit is simply for the purpose of intercepting IC from overheating, and not for protecting and assuring IC. Therefore do not continue to use IC thereafter with this circuit operating and do not use IC assuming the operation of this circuit.
- 10) Inspection with a set board  
When connecting a capacitor to a pin with low impedance in inspection on a set board, stress may possibly be applied to IC, therefore be sure to apply discharging in each process. In attaching to and detaching from jigs in inspection process, be sure to turn off power before connecting, and turn off power before removing IC. In addition, apply grounding to assembling process as a measure of anti-static electricity, and use full caution in transporting and storing.
- 11) GND wiring pattern  
When there are small signal GND and large current GND, separate the large current GND pattern from small signal GND pattern. It is recommended to apply one-point grounding at the reference point of the set in order that resistance of wiring pattern and large current do not cause change of voltage of small signal GND. Please be cautious not to fluctuate the wiring pattern of GND of external mounted parts.
- 12) Capacitor between output and GND  
When a large capacitor is connected between output and GND, if Vcc is shorted with 0V or GND for some cause, it is possible that the current charged in the capacitor may flow into the output resulting in destruction. Keep the capacitor between output and GND below 100uF.
- 13) IC terminal input  
When Vcc voltage is not applied to IC, do not apply voltage to each input terminal. When voltage above Vcc or below GND is applied to the input terminal, parasitic element is actuated due to the structure of IC. Operation of parasitic element causes mutual interference between circuits, resulting in malfunction as well as destruction in the last. Do not use in a manner where parasitic element is actuated.

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